Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP ProCurve Integrated Access Mamager 760wl (J8155A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	12
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Head Screwdrivers	P1 and P0
Torx screwdriver	T8
Wire stripper/cutter	
Flat Head screwdriver	1/8"
Pozidriv screwdriver	1 Pt

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove screws securing top cover using Phillips screwdrive P1. Remove cover
2. Disconnect 40 pin flat cable from PCA motherboard to Hard Drive
3. Unscrew and remove 2 Phillips screws on left side chasis securing Hard Drive Assy
4. Unscrew and remove 2 phillips screws inside the chassis securing Hard Drive Assy
5. Unplug 3 set of cables from Hard Drive (Flat 40 pin, P8 and P9 power cables
6. Remove Hard Drive Assembly
7. Remove 4 phillips screws attaching hard drive to metal bracket using P1 Phillips screwdriver
8. Remove 4 Torx (T8) screws attaching small PCB to Hard Drive
9. Remove small PCA from Hard Drive
10. Disconnect rear fan cables from main PCA. Repeat procedure for each fan
11. Remove 4 phillips screws securing fans to rear Chasis. Repeat process for each fan. Remove fans.
12. Disconnect from main PCB a 20 pin connector and 4 pin connectors from power supply
13. Disconnect cables from the front small PCA assembly (LCD display) to motherboard
14. Disconnect all remaining cables connected to the PCB motherboard
15. Disconnect small cable from Heat sink fan to motherboard
16. Remove large Heat sink by first moving the 2 grey levers 180 degrees each in the oposing direccion until top fan assembly become loose, using a flat screwdriver (1/8') pry-off each plastic anchor end until fan assembly comes off. Remove Heat sink
17. Using Phillips P0 screwdriver remove 4 screws attaching the small PCA assembly (LCD display) to the front sheet metal. Remove LCD assembly
18. Remove 9 pozidriv screws attaching main PCA to Chassis.
19. Remove front small plate that house the RS-232 connector in the front chassis by removing 2 screws (use Phillips P1 screwdriver)
20. Remove all 6 screws that attach the 3 RS-232 connectors using a Nutdriver P6
21. Remove or cut off cables from PCA motherboard to back side of chassis.
22. Remove 9 pozidriv screws attaching mother board to main chassis
23. Remove PCA motherboard from chassis
24. Using a P1 screwdriver remove screws that hold slots (1, 2 or 3) covers (front main sheet metal)
25. Remove any additional RAM memory or any small boards attached to motherboard with sockets
26. Remove battery from motherboard
27. Remove power suppy by removing 1 phillips screw (P0) at the upper power supply oppening in the back of the chassis (screw is located between the two smaller power supply fans) ; remove also one phillips (P0) screw on the left side of chassis near the front holding power supply assembly
28. Slide down power supply assembly and pull it out
29. Remove and disassemble power supply P/N:9PA460050 by first removing rear end bracket. Using a Phillips P1 screwdriver remove the two screws that hold assembly together to power supply box Cut-off cable tie that holds the cable bundle to the bracket.
30. Remove 8 phillips screws (using P1 screwdriver) holding upper plate to main power supply box. Remove plate.
31. Using a wire stripper/cutter cut off all cables and bundles that goes into power supply.
32. Using a P1 phillips screwdriver remove 4 screws that hold main power supply board to power supply chassis. Remove PCA from sheet metal.

33. Using a P1 phillips screwdriver unscrew power supply fans attached to sheet metal. Repeat process for each fan. Remove fans. Use a P1 screwdriver to remove 4 screws that hold fan and connector bracket to power supply sheet metal. Remove fans and main three prong VAC connector .
34. Using a P1 screwdriver remove 1 phillips screw that holds a small PCA to main power supply chasis.
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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).